

'ICT - Introduction'

Martin Goosey

Institute of Circuit Technology

Hayling Island

15th September 2010

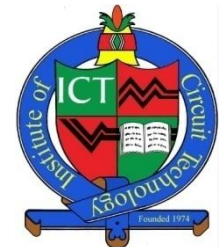


The Institute of Circuit Technology

- The Institute is currently in its 37th year
- It currently has 230 members and is continuing to grow
- Offers a wide and increasing range of services to members

eg; annual symposium, evening seminars, foundation

course, technical journal, website etc



The ICT's New Website

The screenshot shows a Windows Internet Explorer browser window displaying the website for the Institute of Circuit Technology (ICT). The browser's address bar shows the URL <http://www.instct.org/>. The website header features the ICT logo on the left and the title "Institute of Circuit Technology" in red, with the tagline "Interconnecting PCB Professionals" below it. The main content area is divided into three columns. The left column contains two menu boxes: "Main Menu" with links like Home, Welcome, and Join the ICT; and "Members Menu" with links like My Profile and Members Listing. The middle column is titled "About the ICT" and contains a paragraph of text followed by a bulleted list of four points. The right column is a vertical stack of logos for various companies, including ASKbobwillis.com, GRAPHIC, TEKNOflex, CC Electronics Europe, artoteh, invotec, Faraday, Acquia Circuits Limited, FLEX-ABILITY, and STEVENAGE CIRCUITS. At the bottom of the page, there is a "Member Login" section with an email input field and a contact information line.

instct.org - Windows Internet Explorer provided by Loughborough University

http://www.instct.org/

instct.org

Institute of Circuit Technology
Interconnecting PCB Professionals

Main Menu

- Home
- Welcome
- Join the ICT
- News
- Future Events
- Seminar Reports
- Annual Symposium
- Other Events
- Short Circuit
- Who's Who
- Links
- Contact Us
- Make a Payment

Members Menu

- My Profile
- Members Listing
- Seminar Papers
- Symposium Papers
- Technical Papers
- ICT Journal
- Members Forum

Member Login

Email

About the ICT

The ICT was established in 1974. Since then, it has successfully provided technology based training and seminars to the UK's PCB technologists and engineers, keeping them up to speed with developments in the industry. A timeline of notable events in the history of the Institute can be viewed from this link. [History of the Institute pdf](#)

- The ICT is dedicated to technical aspects of Printed Circuit Board Manufacture and Assembly.
- The ICT was originally established as a forum for discussion on technology matters relating to printed circuit interconnection. This has now been expanded to include their assembly and related technology.
- The ICT facilitates this improvement in standards by providing opportunities for its membership to improve their knowledge of manufacturing process technologies, materials, and practices through research, discussion and seminars around the country.
- The ICT operates a grading procedure for membership that will enable industry to measure the levels of specialist education, skills and experience. The membership is graded into Fellow, Member and Associate, designating the level of expertise and experience.

[Grading qualifications and experience pdf](#)
[Objectives of the ICT](#)

For further information about the ICT, contact:

ASKbobwillis.com

GRAPHIC

TEKNOflex

CC Electronics Europe

artoteh

invotec

Faraday

Acquia Circuits Limited

FLEX-ABILITY


STEVENAGE CIRCUITS

Start

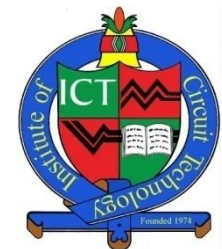
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The Institute of Circuit Technology's Journal

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| <p>vol.3 no.1 January 2010</p> | | <p>2009 Events</p> <p><i>24th September</i> Southern Golf Day and PCB Dinner, Wiltshire Golf Club</p> <p><i>6th October</i> 14.00 ICT Council Meeting - Comfort Inn, 17.00 Evening Seminar - Arundel Supported by Lamar Group</p> <p><i>3rd November</i> 17.00 Evening Seminar, Devonport Hotel, Darlington</p> <p>2010 Events</p> <p><i>28th - 29th</i> EIPC Winter Conference - Toulouse January</p> <p><i>3rd February</i> 13.30 ICT Council Meeting 17.00 ICT AGM - followed by Evening Seminar, Norfolk Hotel, Arundel The event is supported by Isola Group, CCI Eurolam, Vantec Europe and Taconic</p> <p><i>10th February</i> 09.30 leMRC Packaging and Interconnection for Electronics and Sensors past,present and future.Tel:01223 899000 Riverside Offices, Grants Park, Cambridge.</p> <p><i>2nd March</i> 17.00 Evening Seminar, Devonport Hotel, Darlington</p> <p><i>9th -10th</i> National Electronics Week SA March Sandton Convention Centre,Johannesburg</p> <p><i>12th April -</i> Annual Foundation Course , 15th April Loughborough University</p> <p><i>18th - 19th May</i> National Electronics Week UK Hall 1 Birmingham NEC</p> <p><i>9th June</i> 36th Annual Symposium Bracebridge Suite, National Motorcycle Museum at Solihull</p> |
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- Published quarterly
- Currently at Volume 3, Issue 2
- Edited by Bruce Routledge
- Technical papers, news, reviews etc
- New submissions welcome

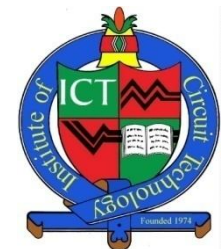
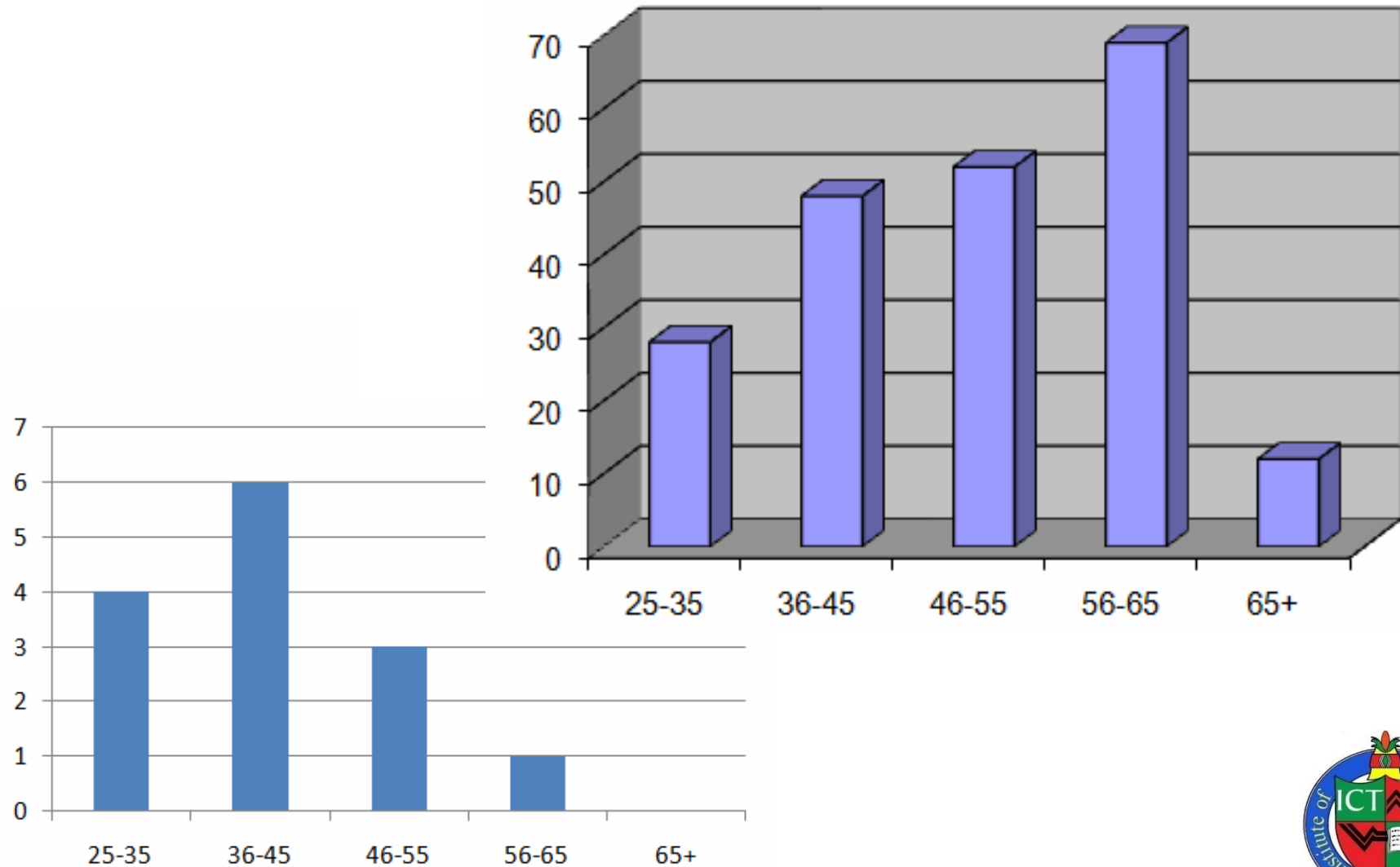


The ICT's Current Programme of Events

| MONTH | ACTIVITY | DATES |
|------------------|--|---|
| JUNE 2009 | Annual Symposium and AGM at Bletchley Park | 4th June |
| AUGUST | Joint ICT/IeMRC/EY Event at Rotherham | 4th August |
| OCTOBER | Evening Seminar at Arundel | 6th October |
| NOVEMBER | Evening Seminar at Darlington | 3rd November |
| FEBRUARY 2010 | Evening Seminar and 2009 AGM at Arundel | 3rd February |
| MARCH | Evening Seminar at Darlington | 2nd March |
| APRIL | Foundation Course at Loughborough | 12 th – 15th April |
| JUNE | Annual Symposium – National Motorcycle Museum | 15 th June |
| SEPTEMBER | Evening Seminar at Hayling Island | 15 th September |
| NOVEMBER | Evening Seminar at Darlington | 2 nd November |
| FEBRUARY 2011 | Evening Seminar at Darlington | 1 st February |
| MARCH 2011 | Evening Seminar at Comfort Inn, Arundel | 1 st March |
| APRIL 2011 | Foundation Course at Loughborough | 4 th – 7 th April |



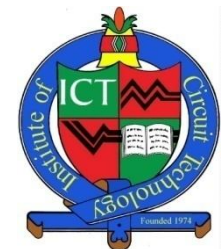
The ICT's Current Membership



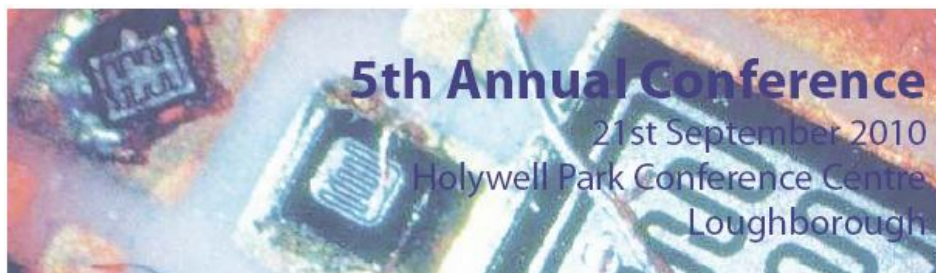
The ICT and the 'ASPIS' FP7 Project

- The Institute is a partner in a bid for European Commission support on an FP7 research project
- Multi-partner project to investigate a range of new technologies related to enhanced nickel gold finishes
- 11 research partners, including 4 large research organisations
- Also includes UK PCB fabricators and the EIPC
- ICT is the project co-ordinator
- Contract signed and due to issued – about to start

| |
|--|
| Institute of Circuit Technology Ltd |
| ITRI Ltd |
| European Institute of Printed Circuits |
| TNO |
| Lithuanian Institute of Chemistry |
| University of Leicester |
| ATOTECH |
| Merlin Circuits Technology |
| Graphic plc |
| Global Interconnection Services |
| Somacis spa |



The leMRC 5th Annual Conference



Agenda

8.30- 9.15 Registration

Session 1 Advanced Packaging

11.00 Morning Break

Session 2 Materials Processing & Assembly

13.00 Lunch

Session 3 Printed Electronics

15.20 Afternoon Break

Session 4 EPSRC

16.10 Close

Breaks and lunch will be held in the main poster display area providing a perfect networking opportunity!

Welcome and Introduction by **Prof Martin Goosey** *leMRC Industrial Director*

Session 1: Advanced packaging

Keynote speech from David Pedder *David Pedder Associates*
'The Role of Flip Chip Bonding in Advanced Packaging'
Norman Stockham *TWI* 'Joining & Packaging Technology for High Temperature Electronics'

Session 2: Materials Processing & Assembly

Anthony Walton *University of Edinburgh* 'The leMRC Flagship Project: SMART MICROSYSTEMS'
Sudipta Roy *Newcastle University* 'Electrochemical Microfabrication without Photolithography - A Sustainable Manufacturing Process'
Marc Desmulliez *Heriot Watt* 'Frequency Agile Microwave Oven Bonding System (FAMOBS): from feasibility study to production prototype'

Session 3: Printed Electronics

Hazel Assender *University of Oxford* 'Introducing the RoVaCBE Flagship project: Roll-to-roll Vacuum processed Carbon Based Electronics'
Steve Jones *Printed Electronics Ltd* 'Printed Electronics: a Review of the State of the Art'
Peter Wilson *University of Surrey* 'Ink Jet Printing & Spin-coating of Electrically Conductive Polymers'

Session 4: EPSRC

Matt Ball *EPSRC* 'The Research Council for Manufacturing'
Closure by **Prof Paul Conway** *leMRC Director*

for registration please email iemrc@lboro.ac.uk

please let us know if you would like to display a poster of your work in the exhibition area

Innovative *electronics* Manufacturing Research Centre
www.iemrc.org

- 21st September in Loughborough
- Covers all aspects of electronics manufacturing
- Completely free to attend
- Great networking opportunity





Thanks to

Spirit Circuits

for their generous sponsorship of today's event